

AMENDMENTS TO THE CLAIMS

Please amend the claims as set forth below:

1. (Currently Amended) A socket to mount and electrically connect an integrated circuit package ~~[[and]]~~ to a circuit board, comprising:

a frame;

a plurality of electrical connectors mounted to the frame;

the plurality of electrical connectors including at least one pair of a power and a ground connector; ~~[[and]]~~

the power connector including a first broadside portion and the ground connector including a second broadside portion, the first and the second broadside portions being disposed in an adjacent, spaced-apart, and substantially parallel relationship;

the power and the ground connectors of the at least one pair including a first and a second mating contact, respectively, disposed to biasingly engage the integrated circuit package; and

the power and the ground connectors of the at least one pair being disposed and configured to be mirror images of each other relative to a geometric plane bisecting a distance between the power and the ground connectors.

2. (Cancelled)

3. (Cancelled)

4. (Currently Amended) The socket according to claim ~~[[3]]~~ 1, wherein the power connector further includes a first arcuate arm portion extending outwardly in a first direction from a first center of one end of the first broadside portion and a first soldering contact mounted on the end of the first arcuate arm and wherein the ground connector further includes a second arcuate arm extending outwardly in a second direction from a second center of one end of the second broadside portion and a second soldering contact mounted on the end of the second arcuate arm, the first and the second

directions being substantially opposite to each other and substantially perpendicular to the geometric plane.

5. (Currently Amended) The socket according to claim 4, wherein the power connector further includes a first bracket portion extending outwardly in the first direction from a first side of the first broadside portion and ~~[[a]]the~~ first mating contact mounted on the end of the first bracket portion and wherein the ground connector further includes a second bracket portion extending outwardly in the second direction from a second side of the second broadside portion and ~~[[a]]the~~ second mating contact mounted on the end of the second bracket portion, the first side and the second side being adjacent to each other.

6. (Currently Amended) An electronic assembly, comprising:

an integrated circuit (IC) package having a first planar surface with a plurality of land pads;

a circuit board having a second planar surface with a plurality of electrical contacts, the second planar surface being disposed in a substantially parallel, spaced-apart relationship with the first planar surface;

a land-grid-array (LGA) socket disposed between the first and the second planar surfaces, the LGA socket including a frame and a plurality of connectors mounted to the frame to electrically couple the land pads of the IC package to the electrical contacts of the circuit board;

the plurality of connectors including at least one pair of a power and a ground connector, with the power and the ground connectors of the pair being disposed and configured to be mirror images of each other relative to a geometric plane substantially bisecting ~~[[the]]~~ a distance between the power and the ground connectors, the geometric plane being substantially perpendicular to the first and the second planar surfaces; and the power and the ground connectors of the at least one pair including a first and a second mating contact, respectively, disposed in biasing engagement with the land pads of the IC package.

7. (Original) The electronic assembly according to claim 6, wherein the power and the ground connectors each include a broadside portion disposed to face each other in an adjacent, spaced-apart and substantially parallel relationship.

8. (Original) The electronic assembly according to claim 6, wherein the power connector includes a first broadside portion and the ground connector includes a second broadside portion, the first and the second broadside portions being disposed in an adjacent, spaced-apart, and substantially parallel relationship.

9. (Currently Amended) The electronic assembly according to claim 8, wherein the power connector further includes a first arcuate arm extending outwardly in a first direction from a first center of one end of the first broadside portion and a first soldering contact mounted on the end of the first arcuate arm and wherein the ground connector further includes a second arcuate arm extending outwardly in a second direction from a second center of one end of the second broadside portion and a second soldering contact mounted on the end of the second arcuate arm, the first and the second directions being substantially opposite to each other and substantially perpendicular to the geometric plane.

10. (Currently Amended) The electronic assembly according to claim 9, wherein the power connector further includes a first bracket portion extending outwardly in the first direction from a first side of the first broadside portion and ~~[[a]]the~~ first mating contact mounted on the end of the first bracket portion and wherein the ground connector further includes a second bracket portion extending outwardly in the second direction from a second side of the second broadside portion and ~~[[a]]the~~ second mating contact mounted on the end of the second bracket portion, the first side and the second side being adjacent to each other.

11. (Currently Amended) A system, comprising:

an electronic assembly including an integrated circuit (IC) package having a first planar surface with a plurality of land pads; a circuit board having a second planar surface with a plurality of electrical contacts, the second planar surface being disposed in a spaced-apart substantially parallel relationship with the first planar surface; a land-grid-array (LGA) socket disposed between the first and the second planar surfaces; the LGA socket including a frame and a plurality of connectors mounted to the frame to electrically couple the land pads of the IC package to the electrical contacts of the circuit board; the plurality of connectors including at least one pair of a power and a ground connector; the power and the ground connectors of the pair being disposed and configured to be mirror images of each other relative to a geometric plane substantially bisecting ~~[[the]]~~ a distance between the power and the ground connectors, the geometric plane being substantially perpendicular to the first and the second planar surfaces; and the power and the ground connectors of the at least one pair including a first and a second mating contact, respectively, disposed in biasing engagement with the land pads of the IC package;

a dynamic random access memory coupled to the electronic assembly; and an input/output interface coupled to the electronic assembly.

12. (Original) The system according to claim 11, wherein the IC package includes a microprocessor and the circuit board is a motherboard.

13. (Original) The system according to claim 11, wherein the input/output interface comprises a networking interface.

14. (Original) The system according to claim 12, wherein the system is a selected one of a set-top box, an entertainment unit and a DVD player.

15. (Original) The system according to claim 11, wherein the power connector includes a first broadside portion and the ground connector includes a second

broadside portion, the first and the second broadside portions being disposed in an adjacent, spaced-apart, and substantially parallel relationship.

16. (Currently Amended) The system according to claim 15, wherein the power connector further includes a first arcuate arm extending outwardly in a first direction from a first center of one end of the first broadside portion and a first soldering contact mounted on the end of the first arcuate arm and wherein the ground connector further includes a second arcuate arm extending outwardly in a second direction from a second center of one end of the second broadside portion and a second soldering contact mounted on the end of the second arcuate arm, the first and the second directions being substantially opposite to each other and substantially perpendicular to the geometric plane.

17. (Currently Amended) The system according to claim 16, wherein the power connector further includes a first bracket portion extending outwardly in the first direction from a first side of the first broadside portion and ~~[[a]]~~the first mating contact mounted on the end of the first bracket portion and wherein the ground connector further includes a second bracket portion extending outwardly in the second direction from a second side of the second broadside portion and ~~[[a]]~~the second mating contact mounted on the end of the second bracket portion, the first side and the second side being adjacent to each other.